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Customer Information Notification	202001029I

Issue Date: 14-Feb-2020
Effective Date: 15-Feb-2020

QUALITY

Management Summary

Release of Errata Document revision forT1024/23 Family of Products

Change Category

☐ Wafer Fab Process ☐ Assembly Process ☐ Product Marking ☐ Test Location ☐ Design

☐ Wafer Fab Materials ☐ Assembly Materials ☐ Mechanical Specification ☐ Test Process ☑ Errata

☐ Wafer Fab Location ☐ Assembly Location ☐ Packing/Shipping/Labeling ☐ Test Equipment ☐ Electrical spec./Test coverage

☐ Firmware ☐ Other

Release of Errata Document Revision for T1024/23 Family of Products

Description

The following changes were made to the errata document for T1024/14 and T1023/13 family of devices:

1- Removed erratum Ethernet A-011436 since it is not applicable.
2- Corrected impacted DDR frequency range for erratum DDR A-009942.

Reason

Notify customers of the errata changes.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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